

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,094,291 B2
APPLICATION NO. : 09/893316
DATED : August 22, 2006
INVENTOR(S) : Reardon et al.

Page 1 of 3

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the Title Page item (56), Include the cited references as listed below:

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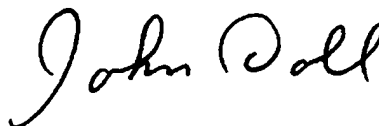
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Signed and Sealed this

Twenty-third Day of June, 2009



JOHN DOLL

Acting Director of the United States Patent and Trademark Office